## Evaluates: MAX14912/MAX14913

#### **General Description**

The MAX14912/MAX14913 evaluation kit (EV kit) provides a proven design to evaluate the MAX14912 or MAX14913 octal digital output driver. The EV kit includes an evaluation board and a graphical user interface (GUI) that provides communication from a PC to the target device through a USB port.

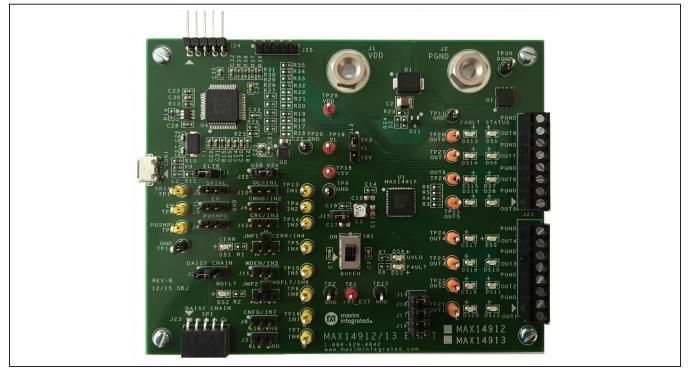
The EV kit includes Windows 7, Windows 8 and Windows 10 compatible software for exercising the features of the IC. The EV kit GUI allows controlling the MAX14912/ MAX14913 in either Parallel Mode or Serial (SPI) Mode. The EV kit must be powered from an external +24V power

supply and can consume up to 10A when fully loaded. The MAX14912EVKIT/MAX14913EVKIT comes with a MAX14912AKN+, or MAX14913AKN+ installed in a 56-pin, 8 x 8mm TQFN-EP package.

### **Features**

- Robust Operation with Wide Range of Input Voltages and Load Conditions
- SPI Interface with up to 20MHz Clock Rate
- Parallel Interface with up to 200kHz Switching Rate
- Manual Control in Parallel Mode
- Wide Logic Voltage Range
- -40°C to +125°C Temperature Range
- On-Board LED Indication of Status and Fault Conditions
- Daisy-Chain Capability
- Reverse-Voltage Protection
- Proven PCB Layout
- Fully Assembled and Tested
- Windows 7, Windows 8 and Windows 10 Compatible Software

Ordering Information appears at end of data sheet.

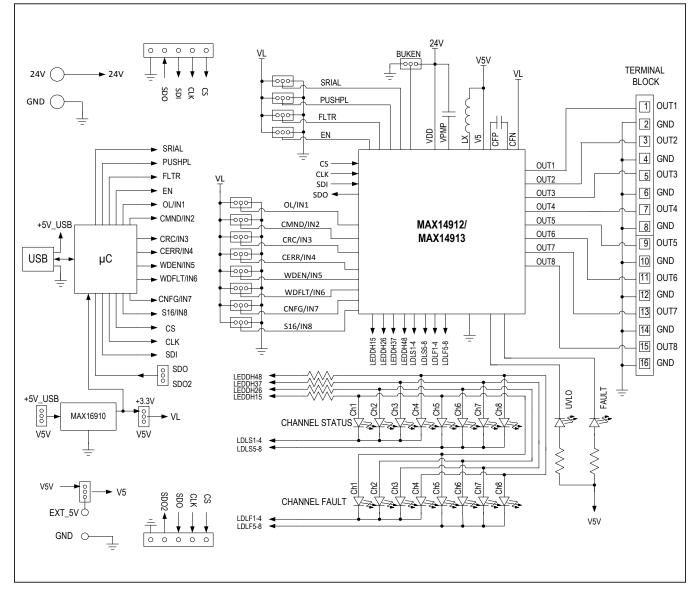


## MAX14912/MAX14913 EV Kit Board Photo



## Evaluates: MAX14912/MAX14913

## System Block Diagram



# Evaluates: MAX14912/MAX14913

#### MAX14912/MAX14913EV Kit Files

FILE	DECRIPTION
MAX14912EVKITSetupV1.0.exe	Application Program (GUI)

### **Quick Start**

#### **Required Equipment**

- MAX14912/MAX14913 EV kit
- +24V power supply
- Voltmeter (optional)
- Oscilloscope (optional)
- PC with installed Windows 7, Windows 8 or Windows 10 and USB port

**Note:** In the following section(s), software-related items are identified by bolding. Text in bold refers to items directly from the EV system software. Text in **bold and underline** refers to items from the Windows operating system.

#### Procedure

The EV kit is fully assembled and tested. Follow the steps below to verify board operation:

- Visit <u>www.maximintegrated.com/evkitsoftware</u> to download the latest version of the EV kit software, MAX14912EVKIT.ZIP. Save the EV kit software to a temporary folder and uncompress the ZIP file.
- Install the EV kit software on your computer by running the MAX14912EVKITSetupV1.0.exe program inside the temporary folder. The program files are copied to your PC and icons are created in the Windows <u>Start</u> <u>| Programs</u> menu.
- 3) Verify that all jumpers are in their default positions for the SPI or parallel mode operation (Table 1). Note that the hardware is configured for SPI communication by default.
- 4) Power up the EV kit with +24V from external power supply.
- 5) Start the EV kit software by opening its icon in the <u>Start | Programs</u> menu. The EV kit software appears as shown in <u>Figure 1</u>. Verify that the lower-right status bar indicates the EV kit hardware is **Connected**. The GUI automatically detects which EV kit is connected to the PC, the MAX14912 or MAX14913, and enables

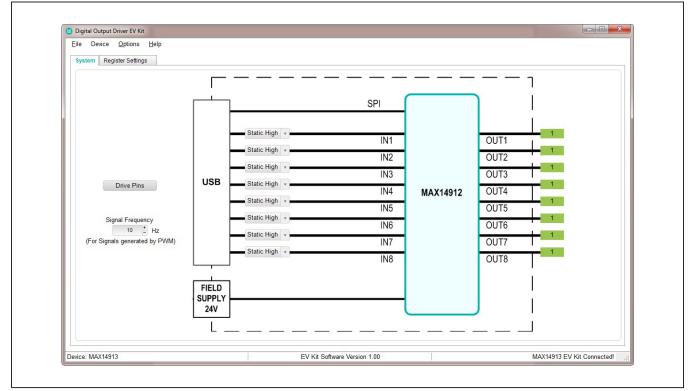


Figure 1. Digital Output Driver EV Kit GUI. System Tab

# Evaluates: MAX14912/MAX14913

## Table 1. MAX14912/MAX14913 Board Shunt Positions and Settings

HEADER	SHUNT POSITION	DESCIPTION
	Open*	Set IN8 high or low/select 16-bit or 8-bit SPI operation in GUI
J3	1-2	Set IN8 high and OUT8 on/high (stand-alone parallel mode)
	2-3	Set IN8 low and OUT8 off/low (stand-alone parallel mode)
	Open*	Set push-pull or high-side mode in GUI
J4	1-2	Set push-pull mode (stand-alone parallel mode)
	2-3	Set high-side mode (stand-alone parallel mode)
	Open*	Enable/disable outputs in GUI
J5	1-2	Enable outputs (stand-alone parallel mode)
	2-3	Disable (three-state) outputs (stand-alone parallel mode)
	Open*	Set IN2 high or low/enable command mode
J6	1-2	Set IN2 high and OUT2 on/high (stand-alone parallel mode)
	2-3	Set IN2 low and OUT2 off/low (stand-alone parallel mode)
17	1-2*	Enable glitch filtering on all parallel logic inputs and $\overline{CS}$
J7	Open	Disable parallel logic glitch filtering
	Open*	Set IN7 high or low/Enable configuration command in GUI
J8	1-2	Set IN7 high and OUT7 on/high (stand-alone parallel mode)
	2-3	Set IN7 low and OUT7 off/low (stand-alone parallel mode)
	Open*	Select serial or parallel interface active in GUI
J9	1-2	Enable serial peripheral interface (SPI)
	2-3	Enable parallel interface (stand-alone parallel mode)
	Open*	Enable/disable open-load detection/Set IN1 in GUI
J10	1-2	Set IN1 high and OUT1 on/high (stand-alone parallel mode)
	2-3	Set IN1 low and OUT1 off/low (stand-alone parallel mode)
	Open*	Enable watchdog timer/set IN5 in GUI
J11	1-2	Set IN5 high and OUT5 on/high (stand-alone parallel mode)
	2-3	Set IN5 low and OUT5 off/low (stand-alone parallel mode)
	Open*	Enable or disable CRC detection/set IN3 in GUI
J12	1-2	Set IN3 high and OUT3 on/high (stand-alone parallel mode)
	2-3	Set IN3 low and OUT3 off/low (stand-alone parallel mode)
14.0	1-2*	Select 3.3V logic level
J13	2-3	Select 5V logic level
J15	1-2*	5V supply. Replace J15 shunt with a current meter to measure power consumption.
116	1-2*	Connect Status and Fault LED anodes for outputs 1 and 5 to the driver
J16	Open	Disconnect Status and Fault LED anodes for outputs 1 and 5 to the driver

# Evaluates: MAX14912/MAX14913

HEADER	SHUNT POSITION	DESCIPTION
J17	1-2*	Connect Status and Fault LED anodes for outputs 2 and 6 to the driver
JI/	Open	Disconnect Status and Fault LED anodes for outputs 2 and 6 to the driver
J18	1-2*	Connect Status and Fault LED anodes for outputs 3 and 7 to the driver
J 18	Open	Disconnect Status and Fault LED anodes for outputs 3 and 7 to the driver
J19	1-2*	Connect Status and Fault LED anodes for outputs 4 and 8 to the driver
119	Open	Disconnect Status and Fault LED anodes for outputs 4 and 8 to the driver
J22	1-2	Select 5V power to U4 from USB port (CON1)
JZZ	2-3*	Select 5V power to U4 from integrated buck regulator (U1)
J26	1-2*	Disable daisy-chain communication
	2-3	Enable daisy-chaining of two boards and use GUI to send a command
	Open*	Enable CRC Error Detection output/Set IN4 high or low in GUI
	1-2	Set IN4 high and OUT4 on/high (stand-alone parallel mode)
JMP1	1-4	Set IN4 low and OUT4 off/low (stand-alone parallel mode)
	1-3	Connect CERR LED (DS1) to U1 to indicate communication error if CRC is enabled on J12
	Open*	Enable watchdog fault output/set IN6 high or low in GUI
	1-2	Set IN6 high and OUT6 on/high (stand-alone parallel mode)
JMP2	1-4	Set IN6 low and OUT6 off/low (stand-alone parallel mode)
	1-3	Connect WDFLT LED (DS2) to U1 to indicate communication error if Watchdog is enabled on J11
0)4/4	2-3, 5-6*	Enable buck regulator of U1 to generate 5V (ON position)
SW1	1-2, 4-5	Disable buck regulator of U1. Provide an external +5V to TP1.

## Table 1. MAX14912/MAX14913 Board Shunt Positions and Settings (continued)

\*Default configuration.

## Evaluates: MAX14912/MAX14913

serial command mode communication. Any configuration change can be made on Register Settings tab. (The following steps are used to verify functionality of the devices.)

- 6) Select System tab.
- 7) Configure each input signal as **Static High** from the pulldown menu, as shown in Figure 1.
- 8) Click on Drive Pins button on the left-side of the GUI.
- Observe all the status LEDs (DS5 to DS12) light up, and measured output voltages on corresponding OUT\_ test point match V<sub>DD</sub> level.
- 10) Change the input signal to **Static Low** from the pulldown menu and observe as corresponding LED turned off.
- Change the input signal to Static PWM. Select the duty cycle from the pulldown menu, refer to Figure 2, and observe the output on corresponding OUT\_test point by oscilloscope.

#### General Description of Software

When the GUI starts, it automatically detects which device is connected to the PC and indicates that in the status bar at the bottom-edge of the GUI. There are two tabs available to control the EV kit. The **System** tab provides system-level control of the selected output pins, including static or dynamic PWM (Pulse-Width Modulation) output in either serial or parallel Mode. The **Register Settings** tab provides full control of the device, including mode selection, per-channel configuration, and enhanced diagnostics of the device. In Serial mode, the SPI clock is set to 5MHz.

#### System Tab

The **System** tab allows driving the output pins by setting up the input signal to the device through the on-board USB to SPI/GPIO bridge IC, U4. Each input pin can be configured as Static High, Static Low, Static PWM, or PWM from the pulldown menu on the input lines in the block diagram shown in the **System** tab. Refer to Figure 3.

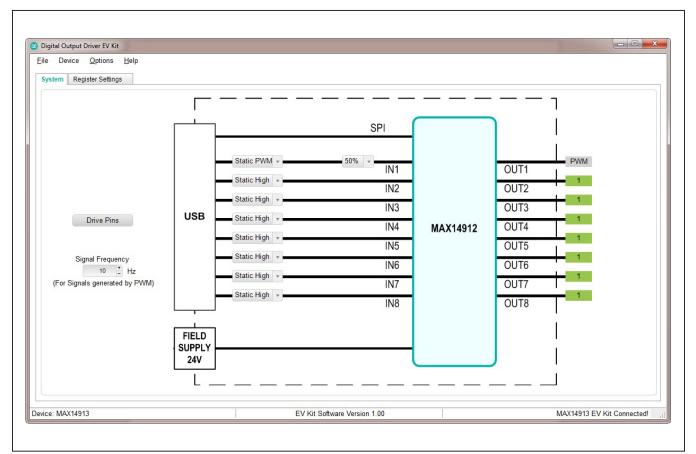


Figure 2. System Tab. Static PWM Configuration

Click **Drive Pins** button on the left-side of the GUI after configuring the inputs. The outputs follow the state of the inputs, while indicators connected to the OUT\_ pins show the static state or dynamic operation mode.

Connect the oscilloscope probe to OUT\_ pin to see the output signal in real-time.

In static PWM and PWM mode, the GUI generates a 1kHz (if SRIAL pin is high) or 20kHz (if SRIAL pin is low) square wave. The level of modulation is selectable from the pulldown menu from 0% to 100%. Refer to Figure 2.

In PWM mode, the signal is modulated by a selected waveform. It can be either a sine wave with a selectable phase, triangle, or sawtooth wave. Refer to Figure 3. The modulation frequency is adjustable from 0Hz up to 60Hz by pressing the + or - buttons. This feature is useful to control small motors, including 3-phase motors, and actuators.

#### **Register Settings Tab**

The **Register Settings** tab is used for detailed configuration of the device to explore all the available features in either parallel (SRIAL is low) or serial (SPI) mode (SRIAL is high). SPI communication is also available in parallel mode with the MAX14912. For a detailed explanation of the features, refer to the MAX14912/MAX14913 data sheet. The mode and pin configuration can be set through the MAX14912 I/O pins control group box on the right-side of the tab. Refer to Figure 4. The pin set slide buttons allow the setting of the input pins high or low, while the read status boxes provide visual colored states of the input/output pins.

The EV kit supports a number of different devices, as listed in Table 3.

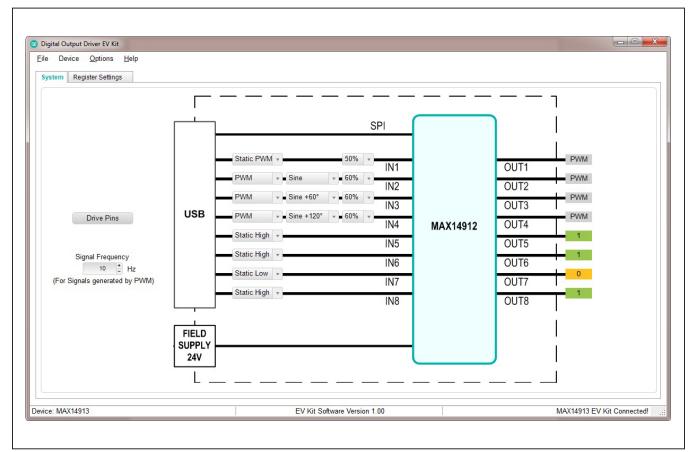


Figure 3. System Tab. PWM Configuration

#### **User-Supplied SPI**

To evaluate the EV kit with a user-supplied SPI bus, disconnect the board from the PC. Apply the user-supplied CS, SCLK (CLK), MOSI (SDI) and MISO (SDO) to the J25 header. Make sure the master ground is connected to the J25.5 ground pin.

The logic level of the external SPI host should be compatible with the J13 shunt selection, (e.g., 3.3V or 5V). Use an external VL logic supply to TP19 to support different logic levels from 1.6V to 5.5V. In this case, J13 shunt should be removed.

#### **Daisy-Chaining**

The two MAX1491X EV kits can be daisy-chained by pairing J24 of board #2 and J23 of board #1 in order to control 16 outputs through a single SPI host. The J26 jumper of board #1 must be set to 2-3 position and both boards have to be powered from an external +24V. The PC should be connected to board #1.

It is also required that board #2 has installed jumpers for SPI communication: J9: 1-2, J5: 1-2, J6: 1-2, J12: 2-3, and J11: 2-3.

The daisy-chain feature is not supported by rev 1.0 GUI and can be evaluated using user-supplied SPI interface. Refer to the MAX14912/MAX14913 data sheet for daisy-chain command description.

#### External +5V Power Supply

An external +5V voltage can supply to TP1, +5V\_EXT. In this case the internal dc-dc controller should be disabled (BUKEN = low) by switching SW1 into off position.

#### **Reverse-Voltage Protection**

The EV kit has reverse-voltage protection circuitry built on the return path of the supply current. During normal operation, the Q1 nMOSFET is ON since the gate voltage is about 7.5V higher than the source. Very low R<sub>ON</sub> of Q1 MOSFET helps to minimize voltage drop and power dissipation to a negligible level. If V<sub>DD</sub> becomes negative with respect to the supply ground, the MOSFET is turned off and disconnects the current path.

#### **Stand-Alone Operation**

The EV kit can work without connecting to a PC. In this case, jumpers should set the inputs, refer to <u>Table 1</u> for proper shunt positions. In stand-alone operation, the devices should be configured for parallel mode. It is recommended to enable internal de-bouncing by placing the J7 shunt for proper operation.

This EV kit comes with two assembly options:

The MAX14912EVKIT# comes with a MAX14912ATE+ in a 56-pin TQFN package.

The MAX14913EVKIT# comes with a MAX14913ATE+ in a 56-pin TQFN package.

Both EV Kit variations use the same PCB and bill of materials, and the only variation is the IC assembled at U1.

# Table 3. Products supported withMAX14912/MAX14913 EV kit

PART #	DESCRIPTION
MAX14912	Octal High-Speed Output Driver
MAX14913	Octal High-Speed Output Driver

# Evaluates: MAX14912/MAX14913

yste	in Regi	ster Setting									
	Addres	s R/W	Register	Value		Description	Auto Read		Read	All	
	0x00	R/W	Switch/Driver Settings	0600000000	Switch/	/Driver Settings	Auto Write		Write Mo	dified	
	0x01	R/W	Push/Pull Configuration	060000000	Push/P	Pull Configuration	Clear Fault Regi	isters U	oon Next \	Vrite	
	0x02	R/W	Open-Load Detect Confi	0b00000000		_oad Detect Configuration					
	0x03	R/W	Watchdog Configuration	000000000		dog Configuration					
	0x04	R	Open Load Condition	060000000		oad Condition					
	0x05	R	Thermal Shutdown Con	0600000000		al Shutdown Condition	MAX14912 I/O pins	5			
	0x06	R	Global Faults Condition	0600000000		Faults Condition	Pin Nane	Set	Setting	Read	Direction (MAX14912)
	0x07	R	Overvoltage	0b00000000	Overvol	Itage	SRIAL	•	Serial	1	IN
Bit Value							PUSHPL		lighSide	0	IN
			Settin	g		Description	EN	C I	Enabled	1	IN
	B[7]		0: HiZ		-						
	B[6]		0: HiZ			Sets Output 7			OpenLoad		IN
	B[5]		0: HIZ			Sets Output 6	CMND/IN2		CMND	1	IN
	B[4]		0: HiZ		-	Sets Output 5	CRC/IN3	$\bigcirc$	CRC	0	IN
	B[3]	0b0	0: HIZ		-	Sets Output 4	CRCE/IN4	$\bigcirc$	CRCE	1	IN (don't care)
	B[2]	0b0	0: HiZ		-	Sets Output 3	WDEN/IN5		VDEN	0	IN
	B[1]	0b0	0: HiZ		-	Sets Output 2	WDFLT/IN6	0	VDFLT	1	IN (don't care)
	B[0]	0b0	0: HiZ		-	Sets Output 1	CNFG/IN7	0	CNFG	0	IN (don't care)
							16bit/8Bit/IN8	0	6bit/8bit	0	IN (don't care)
							Chip Mode \$				
											d Mode 16bit
	Note: To er	lit the value	of a R/W registers, click on th	ne Value cell			SPI 8	bit CME	) + 8bit Da	ita	

Figure 4. Digital Output Driver EV Kit GUI. Register Settings Tab

The two tables on the left side of the tab are the register map (upper table) and bit-by-bit control and description table (lower table). When the register is selected in upper table, the lower table gives the description of each bit and allows changing the register settings using drop down menus for writable registers 0x00 to 0x03. The register setting can be changed directly in the register map table by double clicking on the Value cell. Each data entry should follow by the "Enter/Return" button on the keyboard. The Value cell accepts binary (0b), decimal or hex (0x) numbers and automatically convert them into binary format. The modified register changes its color from black to red until the data will be actually written to the register. There are several write and read options available through the corresponding control buttons on the upper right side of the GUI.

When the **Auto Write** button is selected, any data typed in, or selected through, the **Setting** pulldown menu will be automatically written into the corresponding writable register. The button renamed to **Stop Auto Write** and auto write function can be canceled by clicking on this button second time.

When the **Auto Read** button is selected, the write function is disabled and the GUI is constantly monitoring the status and fault conditions of the device. Clicking a second time on the button, which becomes **Stop Auto Read**, allows canceling this operation.

The Read All button performs a read operation of all registers after each click.

When any fault conditions occur, they will set the bit(s) in the corresponding read-only registers 0x04 to 0x07. The fault conditions should be carefully evaluated and removed externally (overvoltage/under voltage, overload, open load, etc.). After that, select the **Clear Fault Registers Upon Next Write** check box and perform any write/read operation to clear fault bits.

The Write Modified button performs write operation to all modified registers after each click.

# Evaluates: MAX14912/MAX14913

# Component List, PCB Layout, and Schematic

See the following links for component information, PCB layout diagrams, and schematics.

- MAX14912/MAX14913 EV BOM
- MAX14912/MAX14913 EV PCB Layout
- MAX14912/MAX14913 EV Schematics

## **Ordering Information**

PART	TYPE	
MAX14912EVKIT#	EVKIT	
MAX14913EVKIT#	EVKIT	

#Denotes RoHS compliant.

# Evaluates: MAX14912/MAX14913

## **Revision History**

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
0	3/16	Initial release	—

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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TITLE: Bill of Materials

DATE: 12/11/2015

DESIGN: max14912\_evkit\_b

NOTE: DNI--> DO NOT INSTALL ; DNP--> DO NOT PROCURE

		DNI/			MANUFAC			
TEM	REF_DES	DNP	QTY	MFG PART #	TURER	VALUE	DESCRIPTION	COMMENTS
4	<u></u>			C2225V7C41140CK250AD	TDK		CAPACITOR; SMT (1210); CERAMIC CHIP; 10UF; 50V;	
1	C2	-	1	C3225X7S1H106K250AB	TDK	10UF	TOL=10%; TG=-55 DEGC TO +125 DEGC; TC=X7S	
	00.00.00.010.010				ΤΑΙΥΟ		CAPACITOR; SMT (0805); CERAMIC; 1UF; 35V;	
2	C3-C6, C8, C10, C12,		4.4		YUDEN	1.0UF	TOL=10%; MODEL=GMK SERIES; TG=-55 DEGC TO	
2	C13, C15, C16, C20	-	11	GMK212B7105KG	TUDEN	1.00F	+125 DEGC; TC=X7R CAPACITOR; SMT (0603); CERAMIC CHIP; 0.1UF;	
	07 00 010 001						100V; TOL=10%; TG=-55 DEGC TO +125 DEGC;	
2	C7, C9, C18, C21, C25, C28, C30-C36		10	GRM188R72A104KA35; CC0603KRX7R0BB104	MURATA; TDK	0.1UF	TC=X7R	
3	020, 020, 030-030	-	13	CC0003KKA7K0BB104	IDK	0.10F		
							CAPACITOR; SMT (0805); CERAMIC CHIP; 10UF; 16V; TOL=10%; TG=-55 DEGC TO +125 DEGC; TC=X7S;	
4	C11, C17, C19, C22		4	CGA4J1X7S1C106K125	TDK	10UF	AUTO	
4	011, 017, 019, 022	-	4	CGA4J1X731C100K125	IDK	TUUF	CAPACITOR; SMT (0603); CERAMIC CHIP; 0.22UF;	
							50V; TOL=20%; MODEL=Y5V; TG=-55 DEGC TO +125	
5	C14	_	1	GRM188F51H224ZA01D	MURATA	0.22UF	DEGC; TC=+	
5	014	-	1	GI(111861 31112242A01D	MORATA	0.2201	CAPACITOR; SMT (0603); CERAMIC CHIP; 4.7UF; 25V;	
							TOL=10%; MODEL=C SERIES; TG=-55 DEGC TO +85	
6	C23, C24, C29		3	C1608X5R1E475K080AC	ток	4.7UF	DEGC; TC=X5R	
0	023, 024, 023	-	5		TER	4.701		
					KEMET/VE		CAPACITOR; SMT; 0603; CERAMIC; 18pF; 50V; 0.25%;	
7	C26, C27		2	C0603HQN101-180FNP	NKEL	18PF	C0G; -55degC to + 125degC; 0 +/-30PPM/degC	
'	020, 021	-	2					
					HIROSE		CONNECTOR; MALE; SMT; MICRO-USB CONNECTOR	
						7X62RD	MEETING REQUIREMENTS OF USB 2.0 STANDARD;	
8	CON1	-	1	ZX62RD-AB-5P8	CO LTD.		RIGHT ANGLE; 5PINS	MICRO-USB
					LITTELFU			
9	D1	-	1	SMDJ36CA	SE	36V	DIODE; TVS; SMC (DO-214AB); VRM=36V; IPP=51.6A	
-			-		FAIRCHIL			
					D			
					SEMICON	RB751S		
10	D2	-	1	RB751S40	DUCTOR	40	DIODE; SCH; SMT (SOD-523F); PIV=40V; IF=0.03A	
	D11	-		BZX84-A7V5	NXP	7.5V	DIODE; ZNR; SMT (SOT-23); VZ=7.5V; IZ=0.005A	
-						1		
					LITE-ON	LTST-		
	DS1-DS4, DS13-						DIODE; LED; STANDARD; RED; SMT (0805); PIV=5.0V;	
12	DS20	-	12	LTST-C171KRKT	NICS; INC.		IF=0.08A; -55 DEGC TO +85 DEGC	

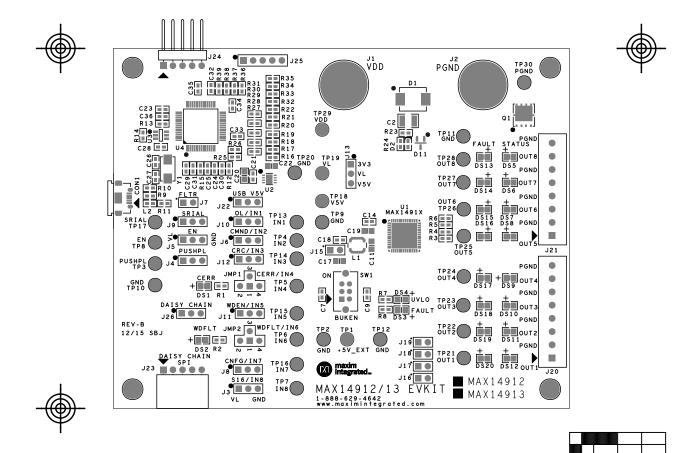
		тт						1
				LITE	-ON	LTST-		
							DIODE; LED; STANDARD; GREEN; SMT (0805);	
13	DS5-DS12	-	8 LTST-C171GKT	NICS	; INC.	Т	PIV=5.0V; IF=0.12A; -55 DEGC TO +85 DEGC	
				POM				
					CTRO		CONNECTOR; MALE; PANELMOUNT; STANDARD	
14	J1, J2	-	2	3267 NICS		3267	UNINSULATED BANANA JACK; STRAIGHT; 1PIN	
							CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY;	
	J3-J6, J8-J13, J22,			0			STRAIGHT THROUGH; 3PINS; -65 DEGC TO +125	
15	J26	-	12 PCC03SAAN	SULI	INS		DEGC	
							CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT THROUGH; 2PINS; -65 DEGC TO +125	
16	J7, J15-J19		6 PCC02SAAN	SULI			DEGC	
10	57, 515-518	-	8 FCC02SAAN	3011	1110	AAN	DEGC	
				ON-				
				SHO	RF			
						OSTTEO	CONNECTOR; MALE; THROUGH HOLE; TERMINAL	
17	J20, J21	-	2 OSTTE080104	OGY			BLOCKS-WIRE TO BOARD; STRAIGHT; 8PINS	
	,						CONNECTOR; FEMALE; THROUGH HOLE; SSQ	
							SERIES; 0.025IN SQ POST SOCKET; RIGHT ANGLE;	
18	J23	-	1 SSQ-105-02-L-S-RA	SAM	TEC	L-S-RA	5PINS	
						TSW-		
							CONNECTOR; MALE; THROUGH HOLE; 0.025IN SQ	
19	J24	-	1 TSW-105-25-T-S-RA	SAM	-	T-S-RA	POST HEADER; RIGHT ANGLE; 5PINS	
				SULL				
				ELEC		DDOOSO	CONNECTOR MALE TURQUOULUOUE REFAVANANA	
20	J25		1 PBC05SAAN	NICS COR		AAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 5PINS; -65 DEGC TO +125 DEGC	
20	JZD	-	I PBC05SAAN	SULL		AAN	STRAIGHT, SPINS, -05 DEGC TO +125 DEGC	
				NICS		PEC04S	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY;	
21	JMP1, JMP2	_	2 PEC04SAAN	COR			STRAIGHT; 4PINS	
- 1	1, onn 2				CRAF		INDUCTOR; SMT; FERRITE BOBBIN CORE; 100UH;	
22	L1	-	1 LPS4018-104MR	T			TOL=+/-20%; 0.56A	100UH
							INDUCTOR; SMT (0603); FERRITE-BEAD; 600; TOL=+/-	
23	L2	-	1 MMZ1608B601C	TDK			25%; 0.5A; -55 DEGC TO +125 DEGC	
				ALPH	HA &			
				OME	GA			
							TRAN; N-CHANNEL SDMOS POWER TRANSISTOR;	
24	Q1	-	1 AON6452	DUC	TOR	2	NCH; DFN8-EP; PD-(2W); I-(26A); V-(100V)	

			CRCW06031001FK; ERJ-	VISHAY DALE; PANASONI			
25	R1, R2, R7, R8	- 4	3EKF1001V	С	1K	RESISTOR; 0603; 1K; 1%; 100PPM; 0.10W; THICK FILM	
26	R3-R6	- 4	CRCW0603470RFK; ERJ- 3EKF4700	VISHAY DALE/PAN ASONIC		RESISTOR, 0603, 470 OHM, 1%, 100PPM, 0.10W, THICK FILM	
27	R9, R10	- 2	2 ERJ-3EKF28R0V	PANASONI C		RESISTOR; 0603; 28 OHM; 1%; 100PPM; 0.10W; THICK FILM	
28	R11, R13, R19	- 3	CRCW060310K0FK; 9C06031A1002FK; ERJ- 3 3EKF1002	VISHAY DALE/YAG EO PHICOMP/ PANASONI C	10K	RESISTOR; 0603; 10K; 1%; 100PPM; 0.10W; THICK FILM	
29	R12	- 1	CRCW060315K0FK	VISHAY DALE	15K	RESISTOR, 0603, 15K OHM,1%, 100PPM, 0.10W, THICK FILM	
30	R14	- 1	CRCW06032K20FK	VISHAY DALE	2.2K	RESISTOR, 0603, 2.2K OHM, 1%, 100PPM, 0.10W, THICK FILM	
31	R15	- 1	CRCW060312K0FK	VISHAY DALE	12K	RESISTOR, 0603, 12K OHM, 1%, 100PPM, 0.10W, THICK FILM	
32	R23	- 1	CRCW06033K00FK	VISHAY DALE	зк	RESISTOR; 0603; 3K OHM; 1%; 100PPM; 0.10W; THICK FILM	
33	R24	- 1	CRCW06031003FK; ERJ- 3EKF1003	VISHAY DALE/PAN ASONIC	100K	RESISTOR; 0603; 100K; 1%; 100PPM; 0.10W; THICK FILM	
34	R25-R39	- 15	CRCW06030000ZS; MCR03EZPJ000; ERJ- 3GEY0R00	VISHAY DALE/ROH M/PANAS ONIC		RESISTOR; 0603; 0 OHM; 0%; JUMPER; 0.10W; THICK FILM	
35	SCREW1-SCREW4	- 4	EVKIT_STANDOFF_M2.5_20	?		KIT; ASSY-STANDOFF20MM; 1PC. STANDOFF/FEM/HEX/M2.5/(20MM)/ALUMINUM; 1PC. SCREW/SLOT/PAN/M2.5/(6MM)/STEEL; ZINC PLATE	
36	SU1-SU11	- 11	SX1100-B	KYCON	SX1100- B	TEST POINT; JUMPER; STR; TOTAL LENGTH=0.24IN; BLACK; INSULATION=PBT;PHOSPHOR BRONZE CONTACT=GOLD PLATED	
37	SW1	- 1	EG2207	E-SWITCH	EG2207	SWITCH; DPDT; THROUGH HOLE; STRAIGHT; 30V; 0.2A; SWITCH SLIDE DPDT 200MA 30V; RCOIL=0 OHM; RINSULATION=0 OHM	

	TP1, TP18, TP19,				KEYSTON		TESTPOINT WITH 1.80MM HOLE DIA, RED,
	TP29	-	4	5010		N/A	MULTIPURPOSE;
	TP2, TP9-TP12, TP20, TP30	-	7		KEYSTON	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; BLACK; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
40	TP3-TP8, TP13-TP17	-	11	5014	KEYSTON E	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; YELLOW; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
41	TP21-TP28	-	8	5013	KEYSTON E	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; ORANGE; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
42	U1	-	1	MAX14912AKN+	MAXIM	12AKN+	IC; SWTC; OCTAL HIGH-SPEED; HIGH-SIDE SWITCH/PUSH-PULL DRIVER; TQFN56-EP
43	U2	-	1	MAX16910CATA8/V+	MAXIM		IC; VREG; EXPOSED PAD 0.2A, AUTOMOTIVE, ULTRA- LOW QUIESCENT CURRENT, LINEAR REGULATOR; TDFN8-EP 150MIL
44	U3	-	1	93LC66BT-I/OT	MICROCHI P		IC; EPROM; 4K MICROWIRE SERIAL EEPROM; SOT23- 6
45	U4	-	1	FT2232HL	FUTURE TECHNOL OGY DEVICES INTL LTD.		IC; MMRY; DUAL HIGH SPEED USB TO MULTIPURPOSE UART/FIFO; LQFP64
46	Y1	-	1	ABM7-12.000MHZ-D2Y-T	ABRACON	12MHZ	CRYSTAL; SMT ; 18PF; 12MHZ; +/-20PPM; +/-30PPM
	MICRO_USB_CABLE	DNI		AK67421-1-R	ASSMANN	AK6742	CONNECTOR; MALE; USB; USB2.0 MICRO CONNECTION CABLE; USB B MICRO MALE TO USB A MALE; STRAIGHT; 5PINS-4PINS
48	SU12-SU20	DNI	9	SX1100-B	KYCON	SX1100- B	TEST POINT; JUMPER; STR; TOTAL LENGTH=0.24IN; BLACK; INSULATION=PBT;PHOSPHOR BRONZE CONTACT=GOLD PLATED
49	C1	DNP	1	EEV-TG1H102M	PANASONI C		CAPACITOR; SMT (CASE_K16); ALUMINUM- ELECTROLYTIC; 1000UF; 50V; TOL=20%; TG=-40 DEGC TO +125 DEGC

50	D3-D10	DNP			DIODE; SCH; SCHOTTKY RECTIFIER; SMT (SOD-123); PIV=60V; IF=0.5A	
51	R16-R18, R20-R22	DNP	CRCW060310K0FK;	VISHAY DALE/YAG EO PHICOMP/ PANASONI C	RESISTOR; 0603; 10K; 1%; 100PPM; 0.10W; THICK FILM	

maxim integrated	This decoment contains information considered proprietory, and shall net be reproduced whally ar in part, ar disclored to others without specific written parmining.
HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: SILK_TOP

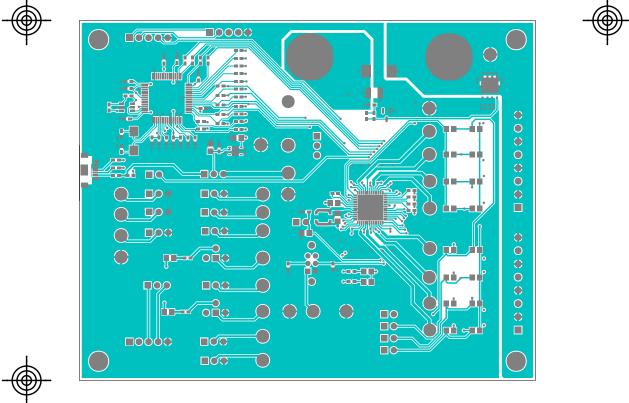


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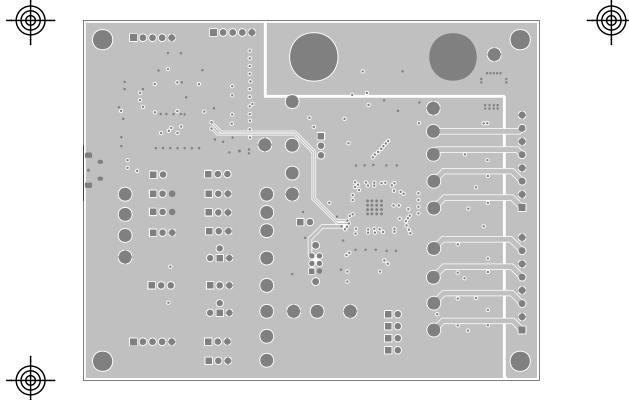
maxim integrated	This deconant contains information considered proprietary, and shall and be reproduced whaty or in part, are disclosed to others allowed specific written presistion.
HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: TOP



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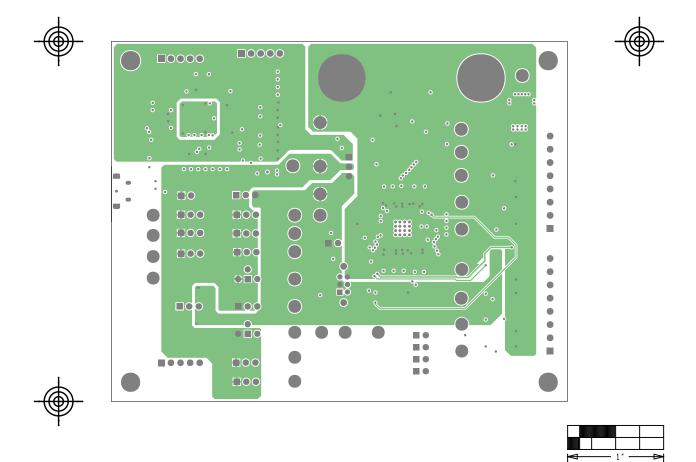
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HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: LAYER2



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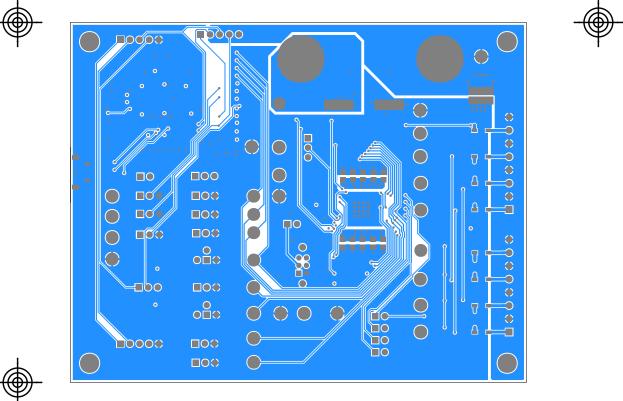


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HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: LAYER3



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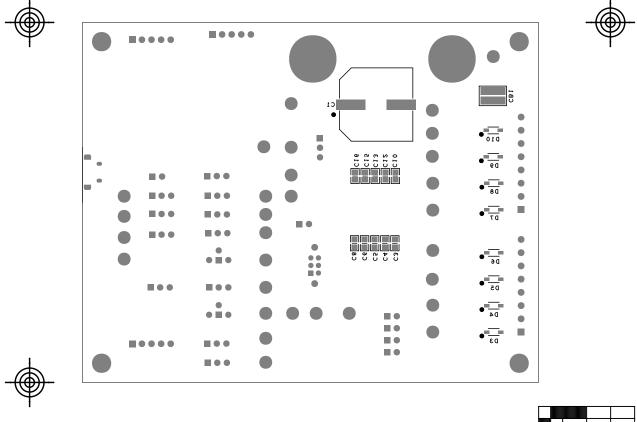
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HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: BOTTOM



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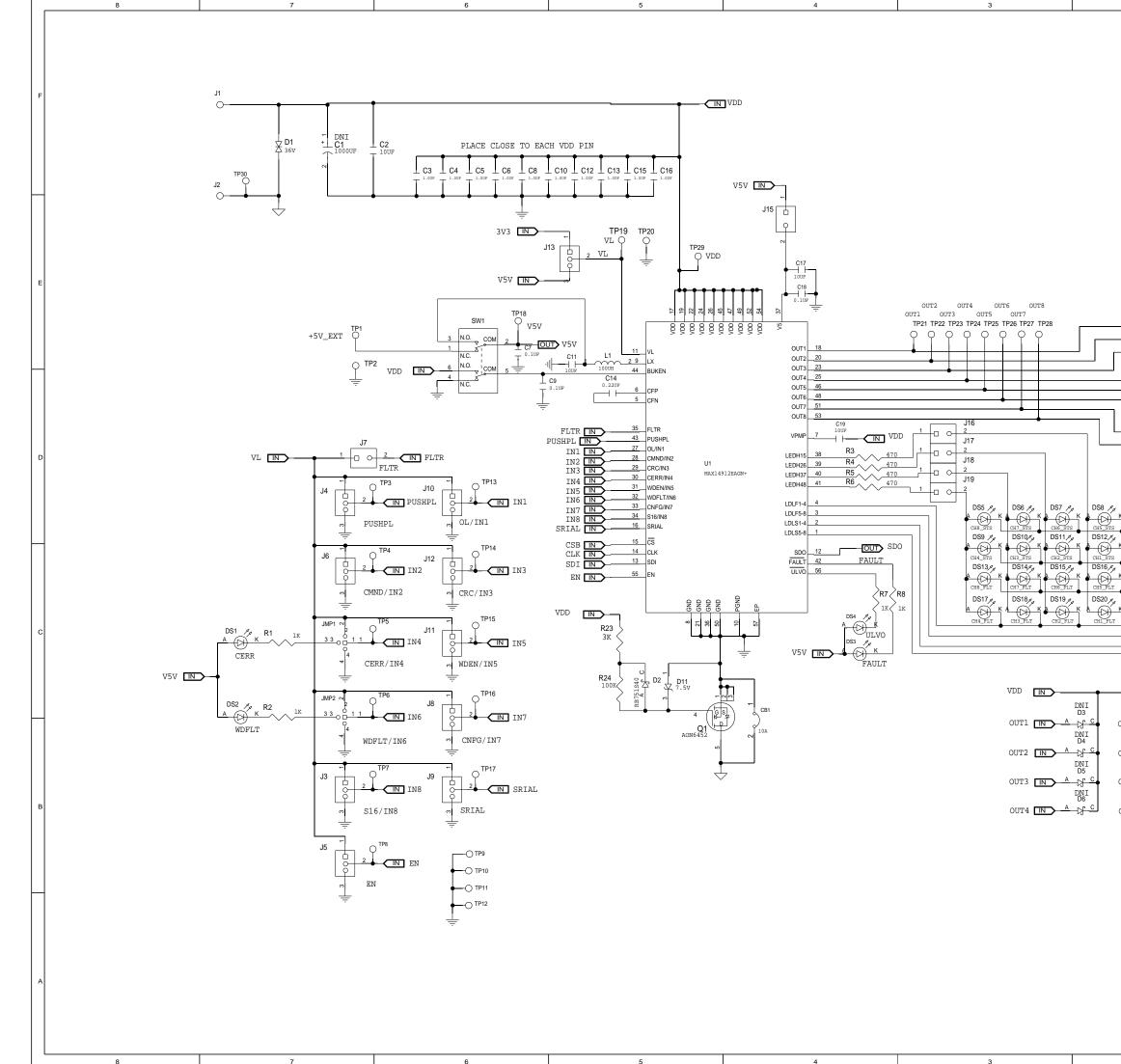


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HARDWARE NAME:MAX14912_EVKIT_B	
HARDWARE NUMBER:	
ENGINEER:	DESIGNER:
DATE: 12/15/2015	ODB++/GERBER: SILK_BOT

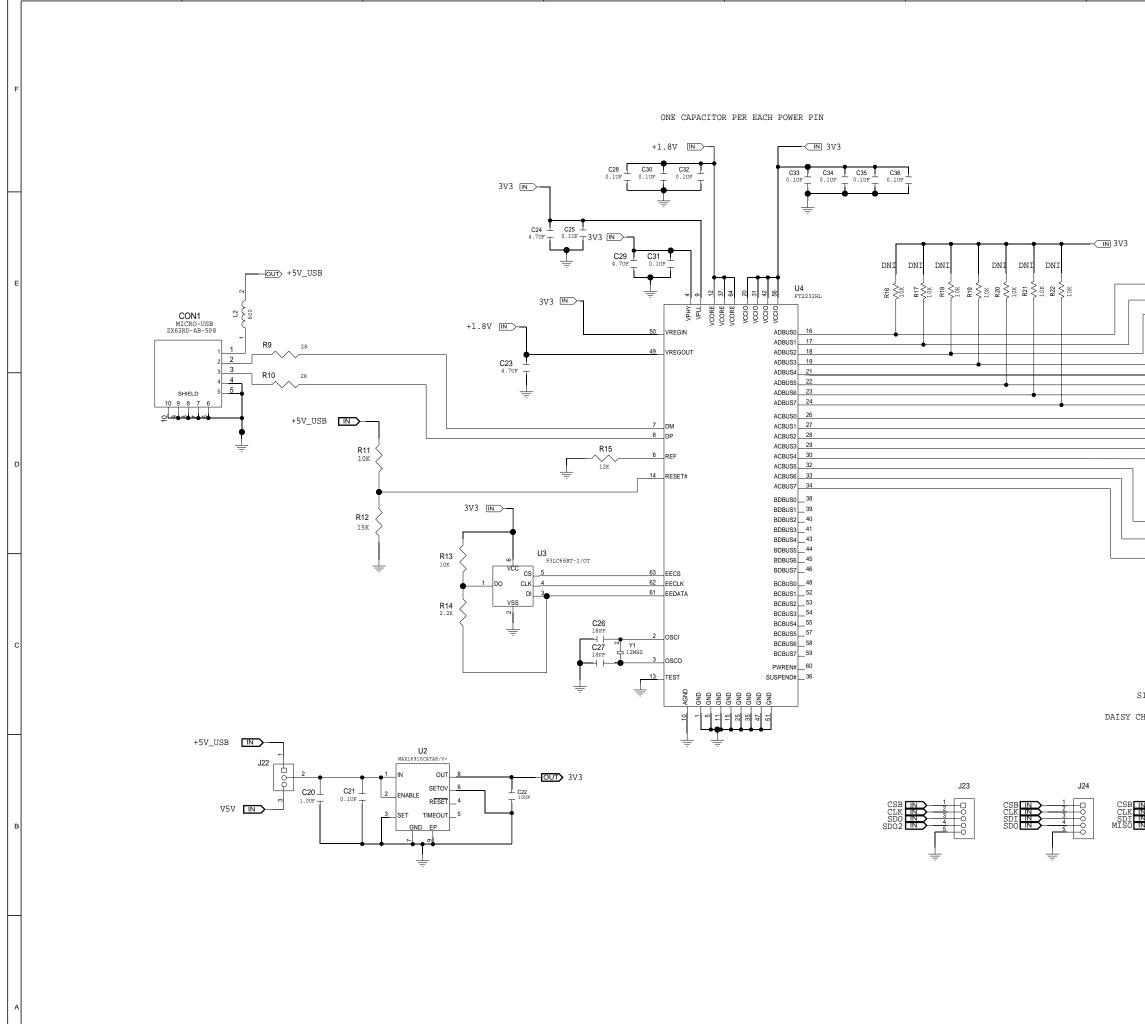


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PROJECT DRAWING SIZE ENGINEEI	G TITLE: DIGITAI HARDWARE N R:	DRAWN BY: TEMPLATE REV	ER	DATE: 12/07/15 REV.: B SHEET 1 OF 2	A



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				F
	R25 ~~ R26 ~~ R27 ~~	CLK CUT SDI MISO		E
	R29 0 R30 0 R31 0 R32 0	OUT CSB OUT PUSHPL IN FAULT OUT EN SRIAL	-	_
	R33 0 R34 0 R35 0 R36 0 R37 0 R37 0 R38 0 R39 0	OUT       IN2         OUT       IN3         OUT       IN4         OUT       IN5         OUT       IN6         OUT       IN7         OUT       IN8		D
	ли Ц —	SDO MISO SDO2		с
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	DRAWING TITLE:	MAX14912 EVKIT B AND MCU		A
-	SIZE HARDWARE NL ENGINEER:		DATE: 12/07/15 REV.: B SHEET 2 OF 2	